

PW-XXXXX

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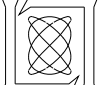
DATE

D.C.N. & DESCRIPTION

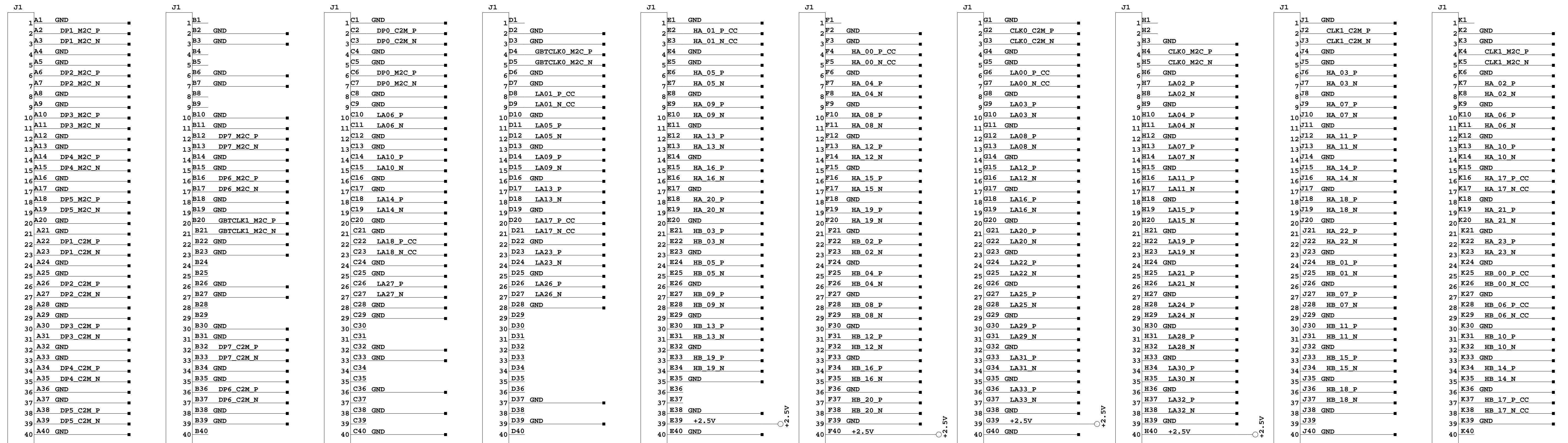
ML605 to USRP FMC Card

Note: Designed to work on the Xilinx ML605 HPC FMC Slot

However, wired for other configurations:
ML605 HPC - Full Functionality
ML605 LPC - 1 Mictor, 1 minisAs
SP605 LPC - 1 Mictor, 1 minisAs
SP601 LPC - 1 Mictor

		DATE	FILENAME	PCB FW#	SHEET#
USED ON	DESIGN FOR	DATE	<div><div>LINCOLN LABORATORY MASSACHUSETTS INSTITUTE OF TECHNOLOGY LEXINGTON, MASSACHUSETTS FOR UNITED STATES GOVERNMENT USE ONLY</div></div>		
	DESIGN BY				
	CHECKED BY				
	PROJECT				
NEXT ASSEMBLY	ENGINEER		SCHEMATIC DIAGRAM DRAWING NAME		
WEIGHT	DATE & PROCESS				
SCALE	STRUCTURES				
CLASSIFICATION	THERMAL				
	MECH. ANALYSIS		PROG-TASK	DWG SIZE	DWG NO. REV

FMC IO Connections



HPC Only

HPC Only

HPC & LPC

HPC & LPC

HPC Only

HPC Only

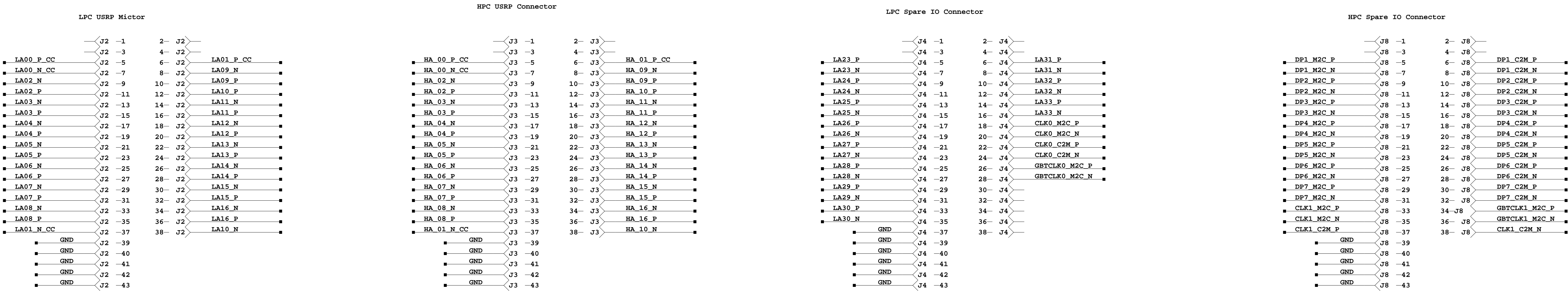
HPC & LPC

HPC & LPC

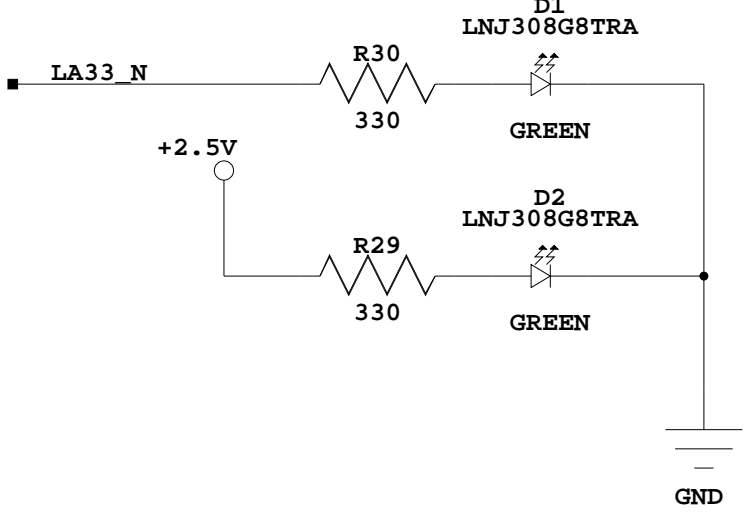
HPC Only

HPC Only

Mictor Connectors



Power and IO LED, NOTE: Reuses LA33N, depop to utilize that IO pin



SERDES Connections

